

a first support plate;

a second support plate proximately positioned with respect to first support plate; and

a cavity plate positioned between the first support plate and the second support plate, the cavity plate having an aperture configured to accept a protruding portion of the circuit package such that the protruding portion of the circuit package contacts the first support plate.

5. (once amended) The system for molding a circuit package, as set forth in claim 4, wherein [a film is disposed between the first support plate on the cavity support plate] the first support plate comprises a film disposed in contact with the protruding portion of the circuit package.

9. (once amended) The system for molding a circuit package, as set forth in claim 1, wherein the [bottom]first support plate contains a plurality of cavity plate push rods.

10. (once amended) The system for molding a circuit package, as set forth in claim 9, wherein the cavity plate push rods are mechanically controlled to separate the cavity plate from the [bottom]first support plate.